

4V Drive Nch+SBD MOSFET

US5U2

●Structure

Silicon N-channel MOSFET /
Schottky barrier diode

●Features

- 1) Nch MOSFET and schottky barrier diode are put in TUMT5 package.
- 2) High-speed switching, Low On-resistance.
- 3) 4V drive.
- 4) Built-in Low V_F schottky barrier diode.

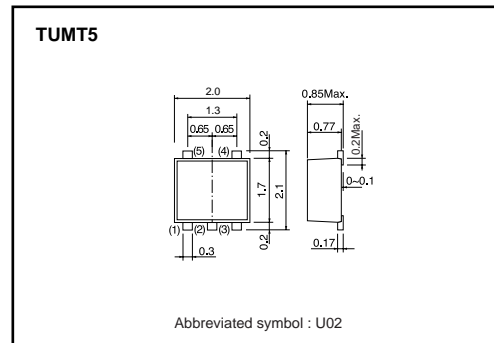
●Applications

Switching

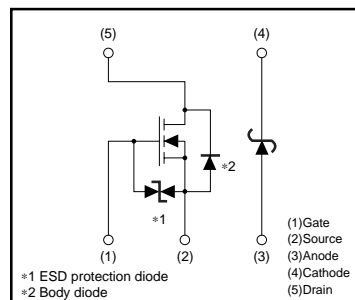
●Packaging specifications

Type	Package	Taping
	Code	TR
	Quantity (pcs)	3000
US5U2		○

●Dimensions (Unit : mm)



●Inner circuit



●Absolute maximum ratings (Ta=25°C)

<MOSFET>

Parameter	Symbol	Limits	Unit	
Drain-source voltage	V_{DSS}	30	V	
Gate-source voltage	V_{GSS}	20	V	
Drain current	Continuous	I_D	± 1.4	A
	Pulsed	I_{DP} *1	± 5.6	A
Source current (Body diode)	Continuous	I_S	0.6	A
	Pulsed	I_{SP} *1	5.6	A
Power dissipation	P_D *2	0.7	W / ELEMENT	
Channel temperature	T_{ch}	150	°C	

*1 $P_w \leq 10 \mu s$, Duty cycle $\leq 1\%$
*2 Mounted on a ceramic board

Transistors

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Parameter	Symbol	Limits	Unit
Repetitive peak reverse voltage	V_{RM}	30	V
Reverse voltage	V_R	20	V
Forward current	I_F	0.5	A
Forward current surge peak	I_{FSM}^{*1}	2.0	A
Power dissipation	P_D^{*2}	0.5	W / ELEMENT
Junction temperature	T_j	150	°C

*1 60Hz · 1cycle

*2 Mounted on ceramic board

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Parameter	Symbol	Limits	Unit
Total power dissipation	P_D^{*1}	1.0	W / TOTAL
Range of storage temperature	T_{stg}	-55 to +150	°C

*1 Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

<MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	–	–	10	μA	$V_{GS}=20V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	30	–	–	V	$I_D=1mA, V_{GS}=0V$
Zero gate voltage drain current	I_{DSS}	–	–	1	μA	$V_{DS}=30V, V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	1.0	–	2.5	V	$V_{DS}=10V, I_D=1mA$
Static drain-source on-state resistance	$R_{DS(on)}^{*}$	–	170	240	mΩ	$I_D=1.4A, V_{GS}=10V$
		–	250	350	mΩ	$I_D=1.4A, V_{GS}=4.5V$
		–	270	380	mΩ	$I_D=1.4A, V_{GS}=4V$
Forward transfer admittance	$ Y_{fs} ^{*}$	1.0	–	–	S	$V_{DS}=10V, I_D=1.4A$
Input capacitance	C_{iss}	–	70	–	pF	$V_{DS}=10V$
Output capacitance	C_{oss}	–	15	–	pF	$V_{GS}=0V$
Reverse transfer capacitance	C_{rss}	–	12	–	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}^{*}$	–	6	–	ns	$V_{DD} \doteq 15V$
Rise time	t_r^{*}	–	6	–	ns	$I_D=0.7A$
Turn-off delay time	$t_{d(off)}^{*}$	–	13	–	ns	$V_{GS}=10V$
Fall time	t_f^{*}	–	8	–	ns	$R_L=21\Omega$
Total gate charge	Q_g^{*}	–	1.4	2.0	nC	$V_{DD} \doteq 15V, V_{GS}=5V$
Gate-source charge	Q_{gs}^{*}	–	0.6	–	nC	$I_D=1.4A$
Gate-drain charge	Q_{gd}^{*}	–	0.3	–	nC	$R_L=11\Omega, R_G=10\Omega$

*Pulsed

<Body diode characteristics (source-drain)>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_{SD}	–	–	1.2	V	$I_S=0.6A, V_{GS}=0V$

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Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	–	–	0.36	V	$I_F=0.1A$
		–	–	0.47	V	$I_F=0.5A$
Reverse current	I_R	–	–	100	μA	$V_R=20V$

Transistors

●Electrical characteristics curves

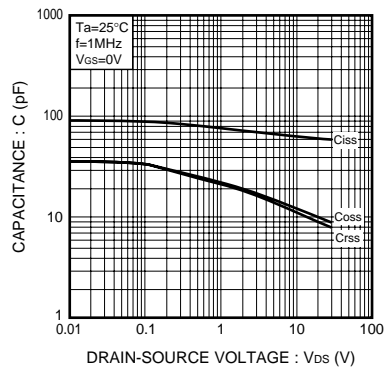


Fig.1 Typical Capacitance vs. Drain-Source Voltage

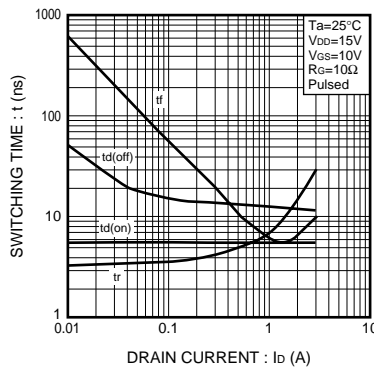


Fig.2 Switching Characteristics

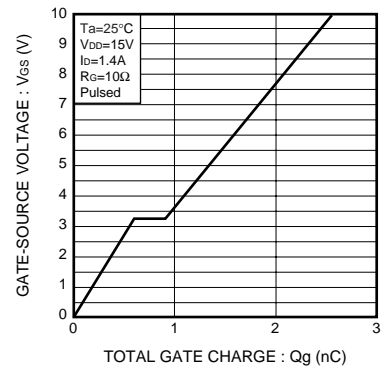


Fig.3 Dynamic Input Characteristics

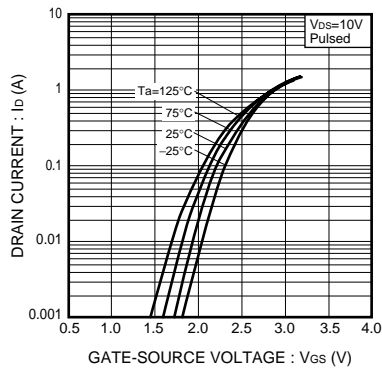


Fig.4 Typical Transfer Characteristics

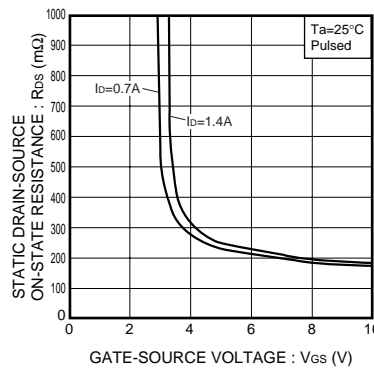


Fig.5 Static Drain-Source On-State Resistance vs. Gate-source Voltage

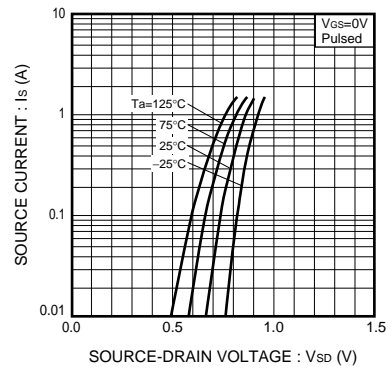


Fig.6 Source Current vs. Source-Drain Voltage

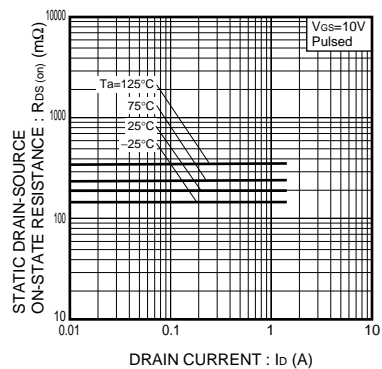


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

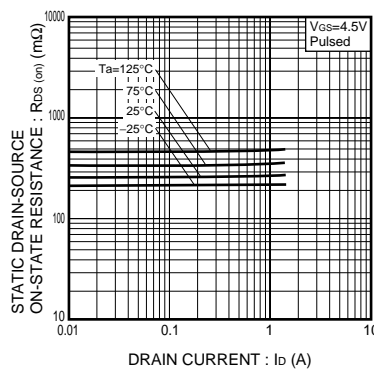


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

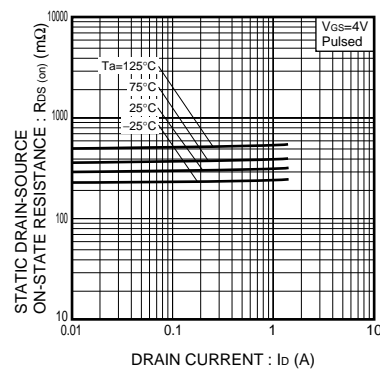


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

Transistors

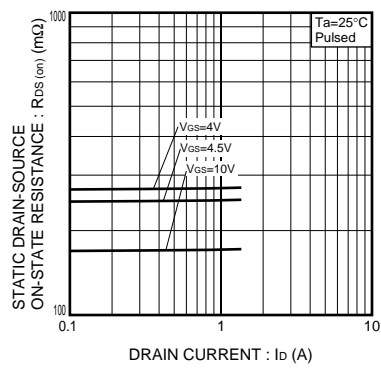


Fig.10 Static Drain-Source On-State Resistance vs. Drain Current (IV)

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - Sealing or coating our Products with resin or other coating materials
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 - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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